

Supporting Information

Thiourea-Based Extraction and Deposition of Gold for Electroless Nickel Immersion Gold Process

Jieun Son^a, Yeongran Hong^b, Cafer T. Yavuz^b, Jong-In Han^{a,}*

^a Department of Civil and Environmental Engineering, Korea Advanced Institute of Science and Technology, 291 Daehak-ro, Yuseong-gu, Daejeon, 34141, Republic of Korea

^b Department of Chemical and Biomolecular Engineering, Korea Advanced Institute of Science and Technology, 291 Daehak-ro, Yuseong-gu, Daejeon, 34141, Republic of Korea

*Corresponding author. E-mail address: hanj2@kaist.ac.kr; Tel: +82-42-350-3629; Fax; +82-42-350-3610

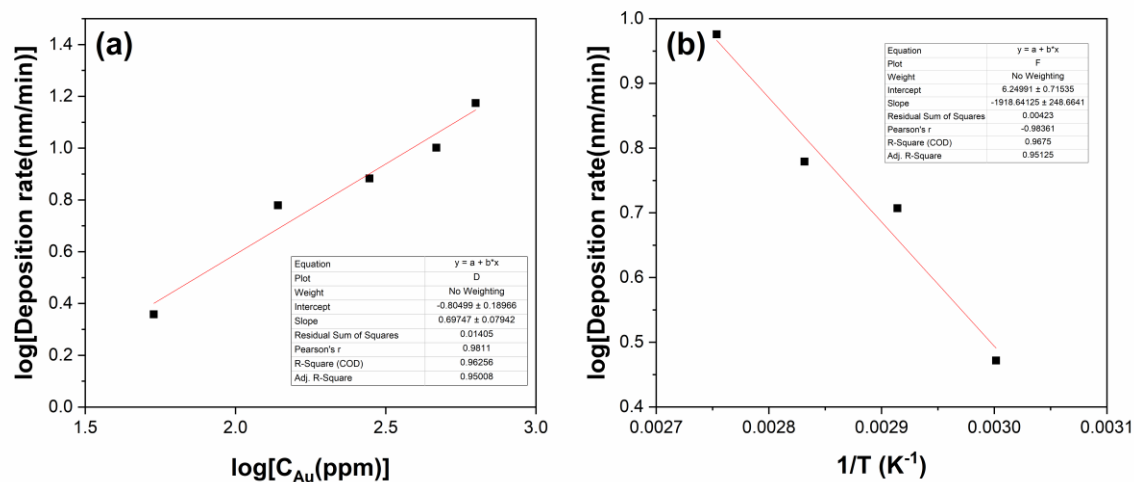


Figure S1. Linear regression of (a) logarithm of deposition rate and gold concentration (b) logarithm of deposition rate and $1/T$.

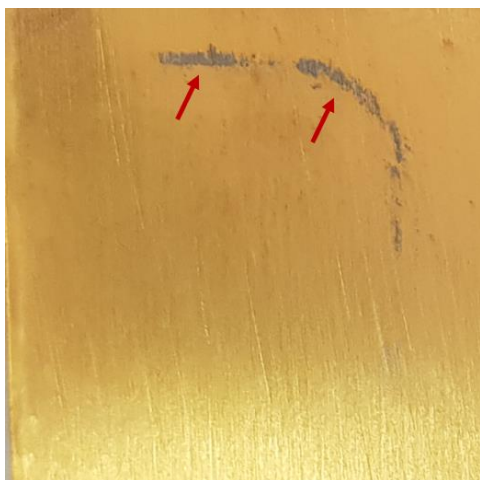


Figure S2. Photographic image of IG coating with the deposition condition of 50 ppm Au after a mild physical attack.